



Material Content Data Sheet



Sales Product Name				IPD65R190C7		Issued		26. September 2017	
MA#				MA001086032					
Package				PG-TO252-3-313		Weight*		321.56 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.186	1.30	1.30	13017	13017	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		458		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		137		
	non noble metal	copper	7440-50-8	147.096	45.76	45.82	457446	458041	
wire	non noble metal	aluminium	7429-90-5	19.241	5.98	5.98	59836	59836	
encapsulation	organic material	carbon black	1333-86-4	1.230	0.38		3824		
	plastics	epoxy resin	-	21.517	6.69		66914		
	inorganic material	silicondioxide	60676-86-0	100.208	31.16	38.23	311630	382368	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.16	1.16	11631	11631	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4418	4429	
solder	noble metal	silver	7440-22-4	0.088	0.03		274		
	non noble metal	tin	7440-31-5	0.070	0.02		219		
	non noble metal	lead	7439-92-1	3.366	1.05	1.10	10468	10961	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	5.96	5.97	59639	59717	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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